

	L #	Hits	Search Text	DBs	Time Stamp
1	L1	2588	(427/488-491, 535-539, 575).CCLS.	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2003/08/05 14:54
2	L2	123678	(conductive adj (polymer plastic monomer dimer oligmer) polyaniline polypyrrole polythiophene aniline pyrrole thiophene)	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2003/08/05 14:57
3	L3	1	1 and mircowave	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2003/08/05 14:58
4	L4	908	1 and microwave	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2003/08/05 14:58

SN10/083,366

	L #	Hits	Search Text	DBs	Time Stamp
5	L5	24	(3 or 4) and 2	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2003/08/0 5 14:59

2

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3

	Document ID	Issue Date	Title	Current OR	Inventor
1	US 2002010 6500 A1	20020808	Plasma curing process for porous low-k materials	428/304.4	Albano, Ralph et al.
2	US 2002001 8897 A1	20020214	Plasma-treated materials	428/409	Kuckert, Christian et al.
3	US 2001003 8919 A1	20011108	Plasma curing process for porous silica thin film	428/446	Berry, Ivan L. III et al.
4	US 6576300 B1	20030610	High modulus, low dielectric constant coating	427/489	Berry, III, Ivan Louis et al.
5	US 6558755 B2	20030506	Plasma curing process for porous silica thin film	427/489	Berry, III, Ivan L. et al.

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(B66) present

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plasma

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10/083, 366

	Document ID	Issue Date	Title	Current OR	Inventor
6	(B24) A further T... conductive poly... plans... (D7) the planet... HF 1/4 micron US 6528170 B2 20030304 C 16 - prod poly A in plasma	20030304	Metal substrate with a corrosion-resistant coating produced by means of plasma polymerization	428/447	Baalman, Alfred et al.
7	(D22) Represent... ...long list... pyrrol, thiophen... ...aniline... US 6503564 B1 20030107	20030107	Method of coating microstructured substrates with polymer layer(s), allowing preservation of surface feature profile	427/255.6	Fleming, Robert J. et al.
8	(D23) Ink part... ...obs. red. c... ...energy = US 6419995 B1 20020716	20020716	Process for the surface activation of materials	427/536	Kuckertz, Christian et al.
9	US 6245150 B1 20010612	20010612	Vapor coating apparatus	118/726	Lyons, Christopher S. et al.

DIV 4 08/1980, 947

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6,528,170
(6E)

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	Document ID	Issue Date	Title	Current OR	Inventor
10	US 6242054 B1 <i>gaw</i> <i>10/26/00</i>	20010605 <i>5/14/99</i> <i>6/16/00</i>	Method for corrosion-resistant coating of metal substrates by means of plasma polymerization	427/489	Baalman, Alfred et al.
11	US 5853819 A <i>(B6)</i> <i>A wide variety of elect. cond. mat. incorp. ... inie conduct. phys.</i> <i>(D9)</i> <i>The glow discharge process</i>	19981229 <i>Comp. Org. Cmp.</i>	Imaging element comprising an electrically conductive layer formed by a glow discharge process	427/537	Lelental, Mark et al.
12	US 5677010 A <i>(B2P3)</i> <i>plasma polymerization</i> <i>(B6)</i> <i>Thiophene ... pyrolytic ...</i>	19971014	Method for producing a polymer coating inside hollow plastic articles	427/489	Esser, Klaus et al.
13	US 5660892 A <i>(D97)</i> <i>Windows films that ...</i> <i>↓ rad ...</i>	19970826 <i>medium 14. ... solid state cond. pol. comp. ...</i>	Method of forming a metallic film	427/537	Robbins, William B. et al.

6

	Document ID	Issue Date	Title	Current OR	Inventor
14	<i>aniline</i> US 5614295 A	19970325	Liquid distribution and retention medium	428/212	Quincy, III, Roger B. et al.
15	<i>(D30) organic amino compounds</i> <i>aniline</i> US 5068146 A	19911126	<i>Polymerized</i> films, medium related members, and process for making	428/336	Nakayama, Masatoshi et al.
16	<i>(D32) other aromatic, methylene, thioether</i> <i>(D39) the plasma generated by RF, microwave, DC or AC source</i> US 4970093 A	19901113	Chemical deposition methods using supercritical fluid solutions	427/575	Sievers, Robert E. et al.
17	<i>AB - plasma</i> US 4869924 A	19890926	Method for synthesis of diamond and apparatus therefor	427/575	Ito, Toshimi chi

50-50 to poor

	Document ID	Issue Date	Title	Current OR	Inventor
18	US 4820580 A	19890411	Process for the production of a composite system of a highly elastic material and a polyurethane foam layer and product formed thereby	428/304.4	Hocker, Jurgen et al.
19	US 4693799 A	19870915	Process for producing plasma polymerized film	204/165	Yanagihara, Kenji et al.
20	US 4686135 A	19870811	Composite sheet material	442/94	Obayashi, Tsutomu et al.

Alb - form 1 in Sulch

18

US 4820580 A

19890411

Process for the production of a composite system of a highly elastic material and a polyurethane foam layer and product formed thereby

428/304.4

Hocker, Jurgen et al.

the time

(D3, D6) DC, LF, HF, ...

US 4693799 A

19870915

Process for producing plasma polymerized film

204/165

Yanagihara, Kenji et al.

(D9) More specific ...

(D14) The silicon rubber ... hardener ... N,N-dimethyl aniline

US 4686135 A

19870811

Composite sheet material

442/94

Obayashi, Tsutomu et al.

Not cold planing ... LF, HF, DC ...

50-50 not pull

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	Document ID	Issue Date	Title	Current OR	Inventor
(B3) 21	US 4396450 A	19830802	Method for bonding elastomers to metals	156/272.6	Blenner, Donald R. et al.
(B3) 22	US 4395434 A	19830726	Method for improving surface properties of shaped articles of synthetic resins	427/536	Imada, Kiyoshi et al.
(B19) 23	US 4199448 A	19800422	Reverse osmosis membrane of high urea rejection properties	210/654	Johnson, Catherine C. et al.
(D0) 24	US 3935330 A	19760127	Two-step coating process	427/487	Smith, Oliver W. et al.

KF or fluor
phosphorus

static
N-cont. poly
In the water
HF = some kHz
managing

Ab - 2 step process
cure w/ EB, UV, plasma, etc... heat
The 2nd step...
microwave heat

(B24) Sand by
anchoring... pyrene...